Special Issue

Advanced Materials for Power Electronics

Message from the Guest Editor

The aim of this Special Issue on “Advanced Materials for Power Electronics” is to capture recent developments in all types of materials for advancing power electronics. These developments include wide bandgap semiconductors for devices, dielectrics for capacitors, soft magnetic materials for inductors and transformers, interconnect and encapsulation materials for packaging, thermal interface materials for cooling, and feedstock materials of additive manufacturing for power electronics packaging and integration. Manuscripts in the form of full research papers, communications, and review articles are encouraged. Keywords

- wide band-gap semiconductor materials for power devices
- dielectrics for power electronics capacitors
- soft magnetic materials for power inductors and transformers
- die-attach, interconnect, and encapsulation materials for power packaging
- thermal interface materials for cooling
- feedstock materials of additive manufacturing for heterogeneous integration

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Deadline for manuscript submissions

closed (15 May 2019)

Materials

an Open Access Journal by MDPI

Impact Factor 3.2
CiteScore 6.4
Indexed in PubMed

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Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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